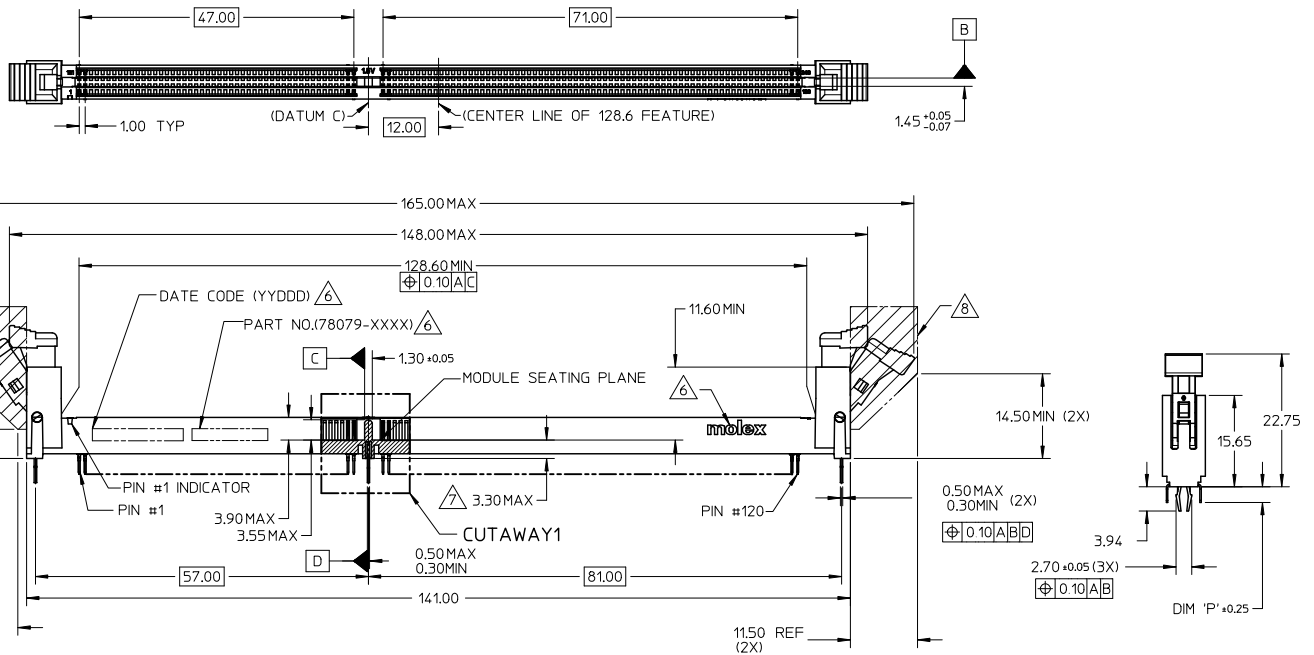


10 9 8 7 6 5 4 3 2 1



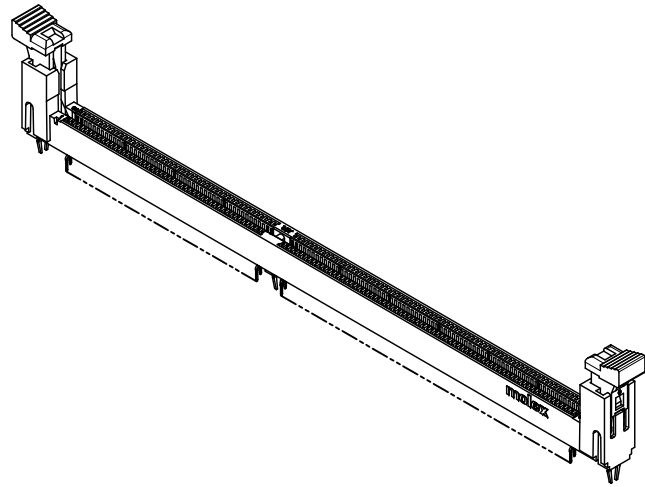
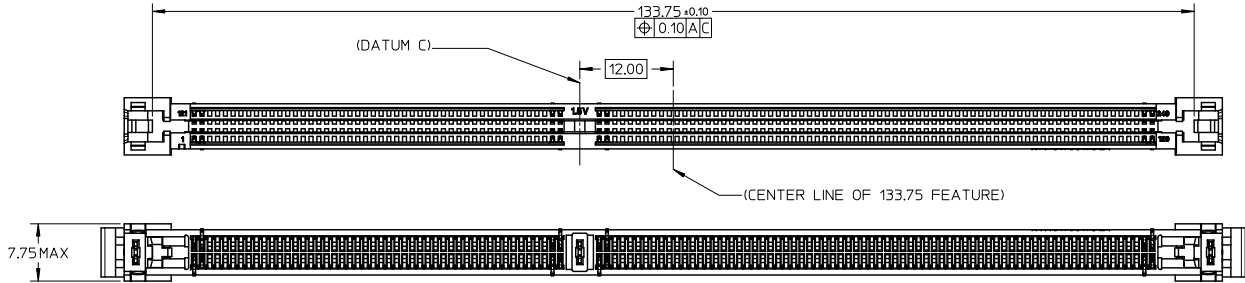
- NOTES :
1. MATERIAL : HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
TERMINAL : COPPER ALLOY.
 2. TERMINAL PLATING OPTIONS: SEE TABLE ON SHEETS 6 & 7.
 3. PRODUCT SPECIFICATION: SEE TABLE ON SHEETS 6 & 7.
 4. PACKAGING INFORMATION: PRODUCT SHALL BE PACKED IN TRAY
 5. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).
6. MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
 7. MODULE SEATING PLANE FROM TOP OF PCB.
 8. KEEP OUT ZONE RESERVED FOR LATCH.

FORKLOCK UPDATED E.C. NO: S2010-0888 DRWN: JAKEEM 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13 REV: A4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																		
	$\nabla=0$ $\nabla=0$ $\nabla=0$	<table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td colspan="3">ANGULAR ± 1°</td> </tr> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	ANGULAR ± 1°			DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H	
		mm	INCH																					
	4 PLACES	± ---	± ---																					
3 PLACES	± ---	± ---																						
2 PLACES	± 0.2	± ---																						
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	MATERIAL NO.	MOLEX INCORPORATED	DOCUMENT NO.	SD-78079-001	SHEET NO. 1 OF 8																		
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																					

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9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

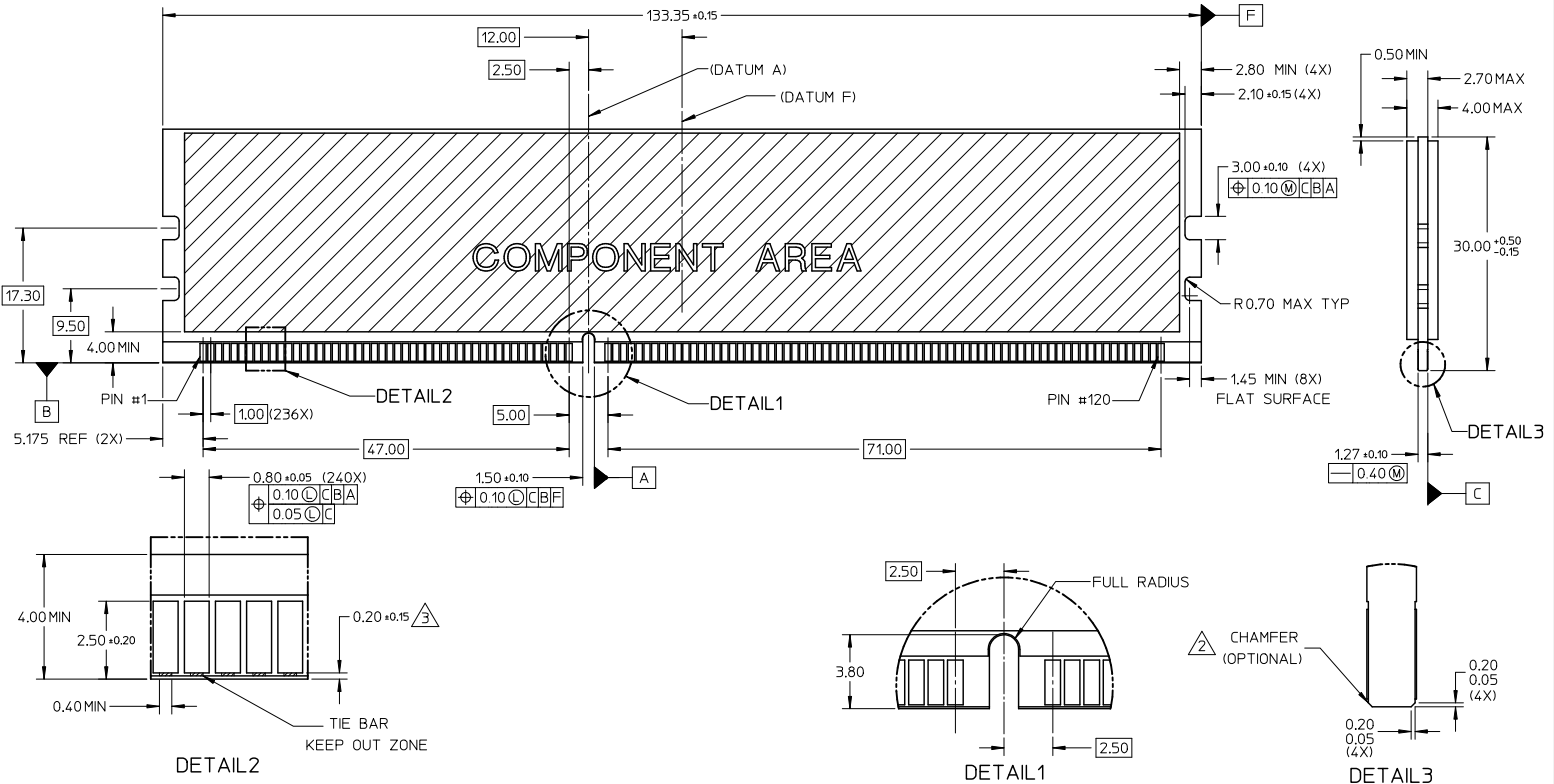


FORK LOCK UPDATED EC NO: S2010-0888 DRWN: JAEHEM 2010/02/29 CHYK: CCEH 2010/06/10 APPR: SHLENI 2010/06/13 A4	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
		2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	CHECKED BY SHLENI	DATE 2006/09/07	APPROVED BY SHLENI			
		ANGULAR ± 1°		APPROVED BY SHLENI		DATE 2010/06/10	MATERIAL NO. SEE TABLE		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SIZE A3		MOLEX INCORPORATED		DOCUMENT NO. SD-78079-001	
								SHEET NO. 2 OF 8	

tb_frame_A3_P_AM_T
Rev. F 2009/06/18

9 8 7 6 5 4 3 2 1

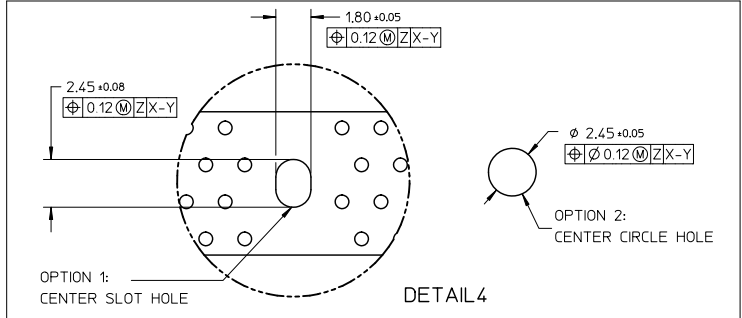
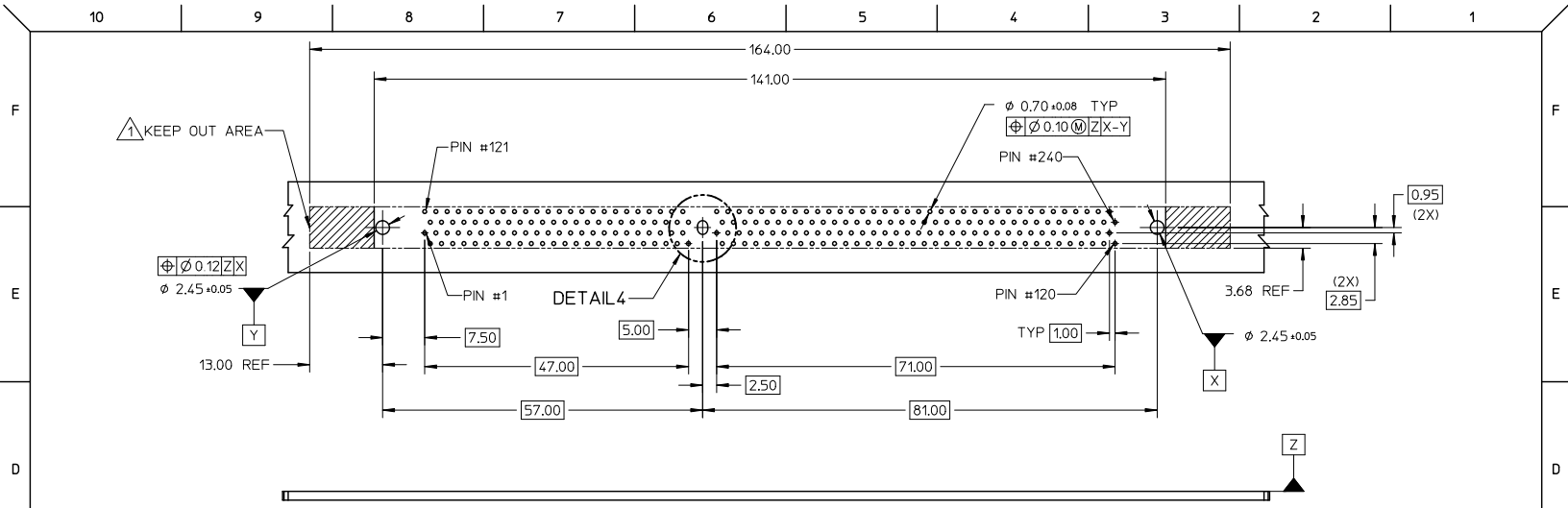
MODULE CARD
DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
(JEDEC MO-269, ISSUE B, MAY 06)



NOTES:

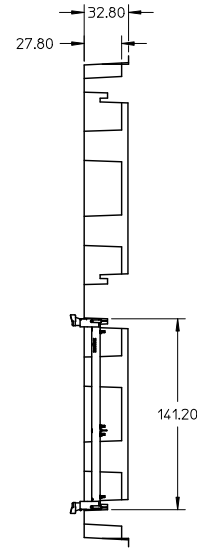
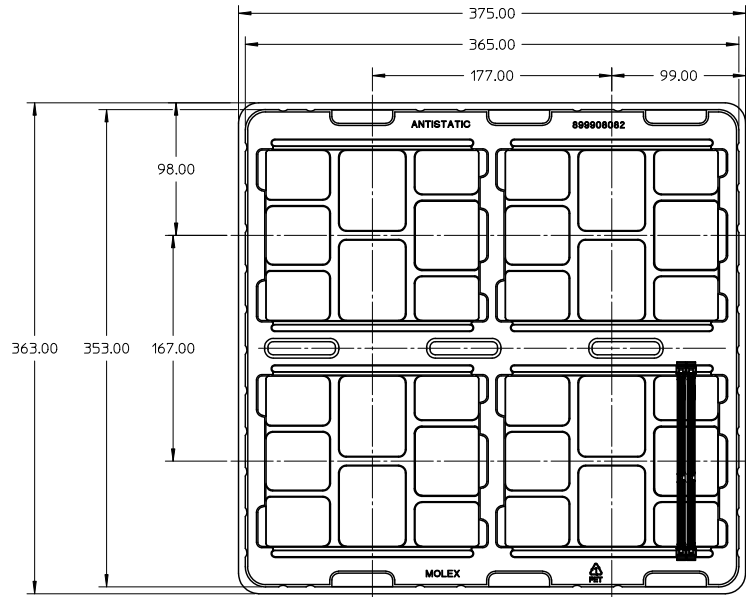
- RECOMMENDED PLATING FOR CONTACT PADS:
PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FORK LOCK UPDATED E.C. NO: S2010-0888 DRWN: JAKEEM CHKD: CTEH APPR: SHLENI 2010/04/29 2010/06/10 2010/06/13	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 1°	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		APPROVED BY SHLENI		DATE 2010/06/10		MATERIAL NO. DOCUMENT NO. SD-78079-001	
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



NOTE:
 ⚠ KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FORKLOCK UPDATED EIC NO: S2010-0888 DRWN: JAEHEM 2010/04/29 CHYK: CTEH 2010/06/10 APPR: SHLENI 2010/06/13 A4	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		NTS	METRIC			
				mm	INCH	DRAWN BY		DATE		TITLE
						YTYANG01		2006/08/11		DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H
				3 PLACES ± --- ± ---		CHECKED BY		DATE		
				2 PLACES ± 0.2 ± ---		SHLENI		2006/09/07		
				1 PLACE ± --- ± ---		APPROVED BY		DATE		
				ANGULAR ± 1°		SHLENI		2010/06/10		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
				SEE TABLE		SD-78079-001		4 OF 8		
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				




NOTES:
1. QTY OF CAVITY: 20 X 4 = 80 PCS

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAEHEM 2010/06/10 CHYK: CTEH 2010/06/10 APPR: SHLENI 2010/06/10	DESCRIPTION REV A4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																											
		$\nabla=0$ $\nabla=0$ $\nabla=0$	<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	<table border="1"> <thead> <tr> <th>DRAWN BY</th> <th>DATE</th> </tr> </thead> <tbody> <tr> <td>YTYANG01</td> <td>2006/08/11</td> </tr> <tr> <th>CHECKED BY</th> <th>DATE</th> </tr> <tr> <td>SHLENI</td> <td>2006/09/07</td> </tr> <tr> <th>APPROVED BY</th> <th>DATE</th> </tr> <tr> <td>SHLENI</td> <td>2010/06/10</td> </tr> </tbody> </table>	DRAWN BY	DATE	YTYANG01	2006/08/11	CHECKED BY	DATE	SHLENI	2006/09/07	APPROVED BY	DATE	SHLENI	2010/06/10	TITLE	DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H	
			mm	INCH																														
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3 PLACES	± ---	± ---																																
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DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78079-001	SHEET NO. 5 OF 8																												

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1


ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION	
78079-0001	CENTRE (1.5V)	BLACK	BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001	
78079-0003				3.00	2.18			
78079-0002				3.18	2.36			
78079-0011				2.67	1.57			
78079-0013				3.00	2.18			
78079-0012				3.18	2.36			
78079-0021			BLACK	BLACK	2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0023					3.00	2.18		
78079-0022					3.18	2.36		
78079-0051					2.67	1.57		
78079-0053					3.00	2.18		
78079-0052					3.18	2.36		
78079-0061			NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0063					3.00	2.18		
78079-0062					3.18	2.36		
78079-0071					2.67	1.57		
78079-0073					3.00	2.18		
78079-0072					3.18	2.36		

FOR KLOCK UPDATED EIC NO: S2010-0888 DRWN: JAKEHEM 2010/04/29 CHKD: CLEH 2010/06/10 APPR: SHLENI 2010/06/13 REV: A4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H
	▽=0	3 PLACES ± --- ± ---		CHECKED BY SHLENI	DATE 2006/09/07	 MOLEX INCORPORATED MATERIAL NO. SEE TABLE DOCUMENT NO. SD-78079-001 SHEET NO. 6 OF 8
	▽=0	2 PLACES ± 0.2 ± ---		APPROVED BY SHLENI	DATE 2010/06/10	
	1 PLACE ± --- ± ---	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

tb_frame_A3_P_AM.T Rev. F 2009/06/18 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1


ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION	
78079-0201	CENTRE (1.5V)	BLUE	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001	
78079-0203				3.00	2.18			
78079-0202				3.18	2.36			
78079-0211				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002
78079-0213				3.00	2.18			
78079-0212				3.18	2.36			
78079-0221		2.67		1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003		
78079-0223		3.00		2.18				
78079-0222		3.18		2.36				
78079-0351		GREEN		2.67	1.57		0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0353				3.00	2.18			
78079-0352				3.18	2.36			
78079-0361				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002	
78079-0363				3.00	2.18			
78079-0362				3.18	2.36			
78079-0371		2.67		1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003		
78079-0373		3.00		2.18				
78079-0372		3.18		2.36				

FORK LOCK UPDATED EC NO: S2010-0888 DRWN: JAKEMEM 2010/04/29 CHKD: CCEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H
	▽=0	3 PLACES ± --- ± ---		CHECKED BY SHLENI	DATE 2006/09/07	 MOLEX INCORPORATED DOCUMENT NO. SD-78079-001 SHEET NO. 7 OF 8
	▽=0	2 PLACES ± 0.2 ± ---		APPROVED BY SHLENI	DATE 2010/06/10	
	1 PLACE ± --- ± ---	ANGULAR ± 1 °		MATERIAL NO. SEE TABLE		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

tb_frame_A3_P_AM.T | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1
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10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION
78079-0101	CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0103				3.00	2.18		
78079-0102				3.18	2.36		
78079-0111				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0113				3.00	2.18		
78079-0112				3.18	2.36		
78079-0121				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0123				3.00	2.18		
78079-0122				3.18	2.36		

FOR KLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEM 2010/06/10 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13 A4	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± --- ± ---	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H
	▽=0	3 PLACES ± --- ± ---		CHECKED BY SHLENI	DATE 2006/09/07	 MOLEX INCORPORATED DOCUMENT NO. SD-78079-001 SHEET NO. 8 OF 8
	▽=0	2 PLACES ± 0.2 ± ---		APPROVED BY SHLENI	DATE 2010/06/10	
		1 PLACE ± --- ± ---		MATERIAL NO. SEE TABLE		
		ANGULAR ± 1°		SIZE A3		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

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